

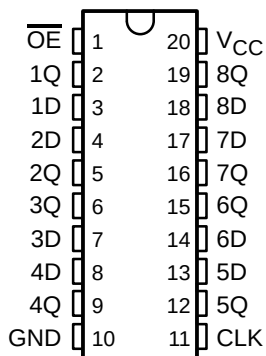
# SN54AHCT374, SN74AHCT374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCLS241L – OCTOBER 1995 – REVISED JULY 2003

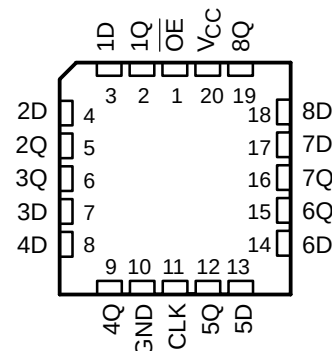
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17

- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

SN54AHCT374 . . . J OR W PACKAGE  
SN74AHCT374 . . . DB, DGV, DW, N, NS, OR PW PACKAGE  
(TOP VIEW)



SN54AHCT374 . . . FK PACKAGE  
(TOP VIEW)



## description/ordering information

The 'AHCT374 devices are octal edge-triggered D-type flip-flops that feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. This device is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels of the data (D) inputs.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

## ORDERING INFORMATION

| T <sub>A</sub> | PACKAGE <sup>†</sup> |               | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|----------------------|---------------|-----------------------|------------------|
| –40°C to 85°C  | PDIP – N             | Tube          | SN74AHCT374N          | AHCT374          |
|                | SOIC – DW            | Tube          | SN74AHCT374DW         |                  |
|                |                      | Tape and reel | SN74AHCT374DWR        | AHCT374          |
|                | SOP – NS             | Tape and reel | SN74AHCT374NSR        |                  |
|                | SSOP – DB            | Tape and reel | SN74AHCT374DBR        | HB374            |
|                | TSSOP – PW           | Tube          | SN74AHCT374PW         | HB374            |
|                |                      | Tape and reel | SN74AHCT374PWR        |                  |
| –55°C to 125°C | TVSOP – DGV          | Tape and reel | SN74AHCT374DGVR       | HB374            |
|                | CDIP – J             | Tube          | SNJ54AHCT374J         | SNJ54AHCT374J    |
|                | CFP – W              | Tube          | SNJ54AHCT374W         | SNJ54AHCT374W    |
|                | LCCC – FK            | Tube          | SNJ54AHCT374FK        | SNJ54AHCT374FK   |

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54AHCT374, SN74AHCT374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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## description/ordering information (continued)

$\overline{OE}$  does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

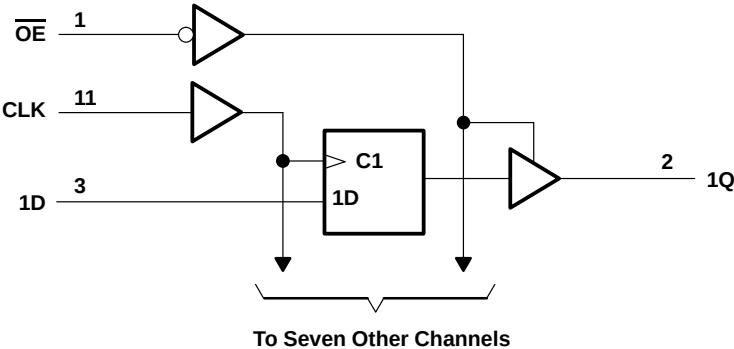
To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

(each flip-flop)

| INPUTS          |        |   | OUTPUT |
|-----------------|--------|---|--------|
| $\overline{OE}$ | CLK    | D | Q      |
| L               | ↑      | H | H      |
| L               | ↑      | L | L      |
| L               | H or L | X | $Q_0$  |
| H               | X      | X | Z      |

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

|                                                                |                            |
|----------------------------------------------------------------|----------------------------|
| Supply voltage range, $V_{CC}$                                 | –0.5 V to 7 V              |
| Input voltage range, $V_I$ (see Note 1)                        | –0.5 V to 7 V              |
| Output voltage range, $V_O$ (see Note 1)                       | –0.5 V to $V_{CC} + 0.5$ V |
| Input clamp current, $I_{IK}$ ( $V_I < 0$ )                    | –20 mA                     |
| Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) | ±20 mA                     |
| Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )     | ±25 mA                     |
| Continuous current through $V_{CC}$ or GND                     | ±75 mA                     |
| Package thermal impedance, $\theta_{JA}$ (see Note 2):         |                            |
| DB package                                                     | 70°C/W                     |
| DGV package                                                    | 92°C/W                     |
| DW package                                                     | 58°C/W                     |
| N package                                                      | 69°C/W                     |
| NS package                                                     | 60°C/W                     |
| PW package                                                     | 83°C/W                     |
| Storage temperature range, $T_{stg}$                           | –65°C to 150°C             |

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

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## recommended operating conditions (see Note 3)

|                 |                                    | SN54AHCT374 |                 | SN74AHCT374 |                 | UNIT |
|-----------------|------------------------------------|-------------|-----------------|-------------|-----------------|------|
|                 |                                    | MIN         | MAX             | MIN         | MAX             |      |
| V <sub>CC</sub> | Supply voltage                     | 4.5         | 5.5             | 4.5         | 5.5             | V    |
| V <sub>IH</sub> | High-level input voltage           | 2           |                 | 2           |                 | V    |
| V <sub>IL</sub> | Low-level input voltage            |             | 0.8             |             | 0.8             | V    |
| V <sub>I</sub>  | Input voltage                      | 0           | 5.5             | 0           | 5.5             | V    |
| V <sub>O</sub>  | Output voltage                     | 0           | V <sub>CC</sub> | 0           | V <sub>CC</sub> | V    |
| I <sub>OH</sub> | High-level output current          |             | –8              |             | –8              | mA   |
| I <sub>OL</sub> | Low-level output current           |             | 8               |             | 8               | mA   |
| Δt/Δv           | Input transition rise or fall rate |             | 20              |             | 20              | ns/V |
| T <sub>A</sub>  | Operating free-air temperature     | –55         | 125             | –40         | 85              | °C   |

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER                     | TEST CONDITIONS                                                                              | V <sub>CC</sub> | T <sub>A</sub> = 25°C |     |       | SN54AHCT374 |      | SN74AHCT374 |      | UNIT |
|-------------------------------|----------------------------------------------------------------------------------------------|-----------------|-----------------------|-----|-------|-------------|------|-------------|------|------|
|                               |                                                                                              |                 | MIN                   | TYP | MAX   | MIN         | MAX  | MIN         | MAX  |      |
| V <sub>OH</sub>               | I <sub>OH</sub> = –50 μA                                                                     | 4.5 V           | 4.4                   | 4.5 |       | 4.4         |      | 4.4         |      | V    |
|                               | I <sub>OH</sub> = –8 mA                                                                      |                 | 3.94                  |     |       | 3.8         |      | 3.8         |      |      |
| V <sub>OL</sub>               | I <sub>OL</sub> = 50 μA                                                                      | 4.5 V           |                       |     | 0.1   |             | 0.1  |             | 0.1  | V    |
|                               | I <sub>OL</sub> = 8 mA                                                                       |                 |                       |     | 0.36  |             | 0.44 |             | 0.44 |      |
| I <sub>I</sub>                | V <sub>I</sub> = 5.5 V or GND                                                                | 0 V to 5.5 V    |                       |     | ±0.1  |             | ±1*  |             | ±1   | μA   |
| I <sub>OZ</sub>               | V <sub>O</sub> = V <sub>CC</sub> or GND, V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> | 5.5 V           |                       |     | ±0.25 |             | ±2.5 |             | ±2.5 | μA   |
| I <sub>CC</sub>               | V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0                                  | 5.5 V           |                       |     | 4     |             | 40   |             | 40   | μA   |
| ΔI <sub>CC</sub> <sup>†</sup> | One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND                                   | 5.5 V           |                       |     | 1.35  |             | 1.5  |             | 1.5  | mA   |
| C <sub>i</sub>                | V <sub>I</sub> = V <sub>CC</sub> or GND                                                      | 5 V             |                       | 4   | 10    |             |      |             | 10   | pF   |
| C <sub>O</sub>                | V <sub>O</sub> = V <sub>CC</sub> or GND                                                      | 5 V             |                       | 9   |       |             |      |             |      | pF   |

\* On products compliant to MIL-PRF-38535, this parameter is not production tested at V<sub>CC</sub> = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

## timing requirements over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

|                 |                                 | T <sub>A</sub> = 25°C |     | SN54AHCT374 |     | SN74AHCT374 |     | UNIT |
|-----------------|---------------------------------|-----------------------|-----|-------------|-----|-------------|-----|------|
|                 |                                 | MIN                   | MAX | MIN         | MAX | MIN         | MAX |      |
| t <sub>w</sub>  | Pulse duration, CLK high or low | 6.5                   |     | 6.5         |     | 6.5         |     | ns   |
| t <sub>su</sub> | Setup time, data before CLK↑    | 2.5                   |     | 2.5         |     | 2.5         |     | ns   |
| t <sub>h</sub>  | Hold time, data after CLK↑      | 2.5                   |     | 2.5         |     | 2.5         |     | ns   |

# SN54AHCT374, SN74AHCT374

## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

### WITH 3-STATE OUTPUTS

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switching characteristics over recommended free-air temperature operating range,  
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

| PARAMETER          | FROM<br>(INPUT)        | TO<br>(OUTPUT) | LOAD<br>CAPACITANCE  | $T_A = 25^\circ\text{C}$ |       |        | SN54AHCT374 |        | SN74AHCT374 |      | UNIT |
|--------------------|------------------------|----------------|----------------------|--------------------------|-------|--------|-------------|--------|-------------|------|------|
|                    |                        |                |                      | MIN                      | TYP   | MAX    | MIN         | MAX    | MIN         | MAX  |      |
| $f_{\text{max}}$   |                        |                | $C_L = 15\text{ pF}$ | 90**                     | 140** |        | 80**        |        | 80          |      | MHz  |
|                    |                        |                | $C_L = 50\text{ pF}$ | 85                       | 130   |        | 75          |        | 75          |      |      |
| $t_{\text{PLH}}$   | CLK                    | Q              | $C_L = 15\text{ pF}$ |                          | 5.6** | 9.4**  | 1**         | 10.5** | 1           | 10.5 | ns   |
| $t_{\text{PHL}}$   |                        |                |                      |                          | 5.6** | 9.4**  | 1**         | 10.5** | 1           | 10.5 |      |
| $t_{\text{PZH}}$   | $\overline{\text{OE}}$ | Q              | $C_L = 15\text{ pF}$ |                          | 6.5** | 10.2** | 1**         | 11.5** | 1           | 11.5 | ns   |
| $t_{\text{PZL}}$   |                        |                |                      |                          | 6.5** | 10.2** | 1**         | 11.5** | 1           | 11.5 |      |
| $t_{\text{PHZ}}$   | $\overline{\text{OE}}$ | Q              | $C_L = 15\text{ pF}$ |                          | 6.2** | 10.2** | 1**         | 11**   | 1           | 11   | ns   |
| $t_{\text{PLZ}}$   |                        |                |                      |                          | 6.2** | 10.2** | 1**         | 11**   | 1           | 11   |      |
| $t_{\text{PLH}}$   | CLK                    | Q              | $C_L = 50\text{ pF}$ |                          | 6.4   | 10.4   | 1           | 11.5   | 1           | 11.5 | ns   |
| $t_{\text{PHL}}$   |                        |                |                      |                          | 6.4   | 10.4   | 1           | 11.5   | 1           | 11.5 |      |
| $t_{\text{PZH}}$   | $\overline{\text{OE}}$ | Q              | $C_L = 50\text{ pF}$ |                          | 7.3   | 11.2   | 1           | 12.5   | 1           | 12.5 | ns   |
| $t_{\text{PZL}}$   |                        |                |                      |                          | 7.3   | 11.2   | 1           | 12.5   | 1           | 12.5 |      |
| $t_{\text{PHZ}}$   | $\overline{\text{OE}}$ | Q              | $C_L = 50\text{ pF}$ |                          | 7     | 11.2   | 1           | 12     | 1           | 12   | ns   |
| $t_{\text{PLZ}}$   |                        |                |                      |                          | 7     | 11.2   | 1           | 12     | 1           | 12   |      |
| $t_{\text{sk}}(0)$ |                        |                | $C_L = 50\text{ pF}$ |                          |       | 1***   |             |        |             | 1    | ns   |

\*\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

\*\*\* On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics,  $V_{CC} = 5\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (see Note 4)

| PARAMETER                 |                                               | SN74AHCT374 |      |      | UNIT |
|---------------------------|-----------------------------------------------|-------------|------|------|------|
|                           |                                               | MIN         | TYP  | MAX  |      |
| $V_{\text{OL}}(\text{P})$ | Quiet output, maximum dynamic $V_{\text{OL}}$ |             | 0.8  | 1.2  | V    |
| $V_{\text{OL}}(\text{V})$ | Quiet output, minimum dynamic $V_{\text{OL}}$ |             | -0.8 | -1.2 | V    |
| $V_{\text{OH}}(\text{V})$ | Quiet output, minimum dynamic $V_{\text{OH}}$ | 3.8         |      |      | V    |
| $V_{\text{IH}}(\text{D})$ | High-level dynamic input voltage              | 2           |      |      | V    |
| $V_{\text{IL}}(\text{D})$ | Low-level dynamic input voltage               |             |      | 0.8  | V    |

NOTE 4: Characteristics are for surface-mount packages only.

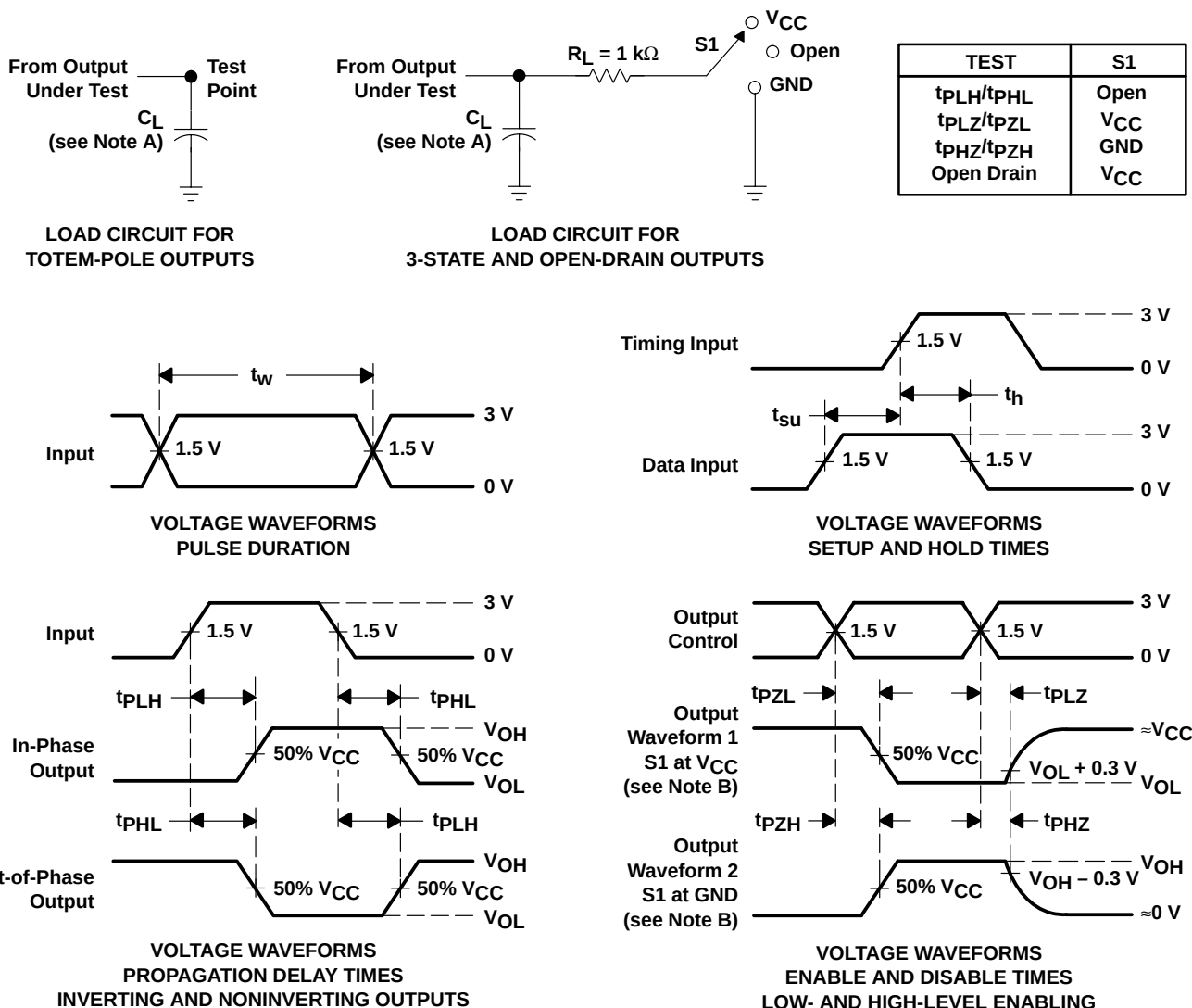
operating characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

| PARAMETER       |                               | TEST CONDITIONS |                    | TYP | UNIT |
|-----------------|-------------------------------|-----------------|--------------------|-----|------|
| $C_{\text{pd}}$ | Power dissipation capacitance | No load,        | $f = 1\text{ MHz}$ | 27  | pF   |

# SN54AHCT374, SN74AHCT374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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## PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)     | Lead finish/<br>Ball material<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5)                   | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|---------------------|--------------------------------------|----------------------|--------------|-------------------------------------------|-------------------------|
| 5962-9686501Q2A  | ACTIVE        | LCCC         | FK                 | 20   | 1              | Non-RoHS<br>& Green | SNPB                                 | N / A for Pkg Type   | -55 to 125   | 5962-<br>9686501Q2A<br>SNJ54AHCT<br>374FK | <a href="#">Samples</a> |
| 5962-9686501QRA  | ACTIVE        | CDIP         | J                  | 20   | 1              | Non-RoHS<br>& Green | SNPB                                 | N / A for Pkg Type   | -55 to 125   | 5962-9686501QR<br>A<br>SNJ54AHCT374J      | <a href="#">Samples</a> |
| 5962-9686501QSA  | ACTIVE        | CFP          | W                  | 20   | 1              | Non-RoHS<br>& Green | SNPB                                 | N / A for Pkg Type   | -55 to 125   | 5962-9686501QS<br>A<br>SNJ54AHCT374W      | <a href="#">Samples</a> |
| SN74AHCT374DBR   | ACTIVE        | SSOP         | DB                 | 20   | 2000           | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 85    | HB374                                     | <a href="#">Samples</a> |
| SN74AHCT374DBRG4 | ACTIVE        | SSOP         | DB                 | 20   | 2000           | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 85    | HB374                                     | <a href="#">Samples</a> |
| SN74AHCT374DW    | ACTIVE        | SOIC         | DW                 | 20   | 25             | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 85    | AHCT374                                   | <a href="#">Samples</a> |
| SN74AHCT374DWR   | ACTIVE        | SOIC         | DW                 | 20   | 2000           | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 85    | AHCT374                                   | <a href="#">Samples</a> |
| SN74AHCT374N     | ACTIVE        | PDIP         | N                  | 20   | 20             | RoHS &<br>Non-Green | NIPDAU                               | N / A for Pkg Type   | -40 to 85    | SN74AHCT374N                              | <a href="#">Samples</a> |
| SN74AHCT374PW    | ACTIVE        | TSSOP        | PW                 | 20   | 70             | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 85    | HB374                                     | <a href="#">Samples</a> |
| SN74AHCT374PWR   | ACTIVE        | TSSOP        | PW                 | 20   | 2000           | RoHS & Green        | NIPDAU                               | Level-1-260C-UNLIM   | -40 to 85    | HB374                                     | <a href="#">Samples</a> |
| SNJ54AHCT374FK   | ACTIVE        | LCCC         | FK                 | 20   | 1              | Non-RoHS<br>& Green | SNPB                                 | N / A for Pkg Type   | -55 to 125   | 5962-<br>9686501Q2A<br>SNJ54AHCT<br>374FK | <a href="#">Samples</a> |
| SNJ54AHCT374J    | ACTIVE        | CDIP         | J                  | 20   | 1              | Non-RoHS<br>& Green | SNPB                                 | N / A for Pkg Type   | -55 to 125   | 5962-9686501QR<br>A<br>SNJ54AHCT374J      | <a href="#">Samples</a> |
| SNJ54AHCT374W    | ACTIVE        | CFP          | W                  | 20   | 1              | Non-RoHS<br>& Green | SNPB                                 | N / A for Pkg Type   | -55 to 125   | 5962-9686501QS<br>A<br>SNJ54AHCT374W      | <a href="#">Samples</a> |

<sup>(1)</sup> The marketing status values are defined as follows:  
**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54AHCT374, SN74AHCT374 :**

- Catalog : [SN74AHCT374](#)
- Military : [SN54AHCT374](#)

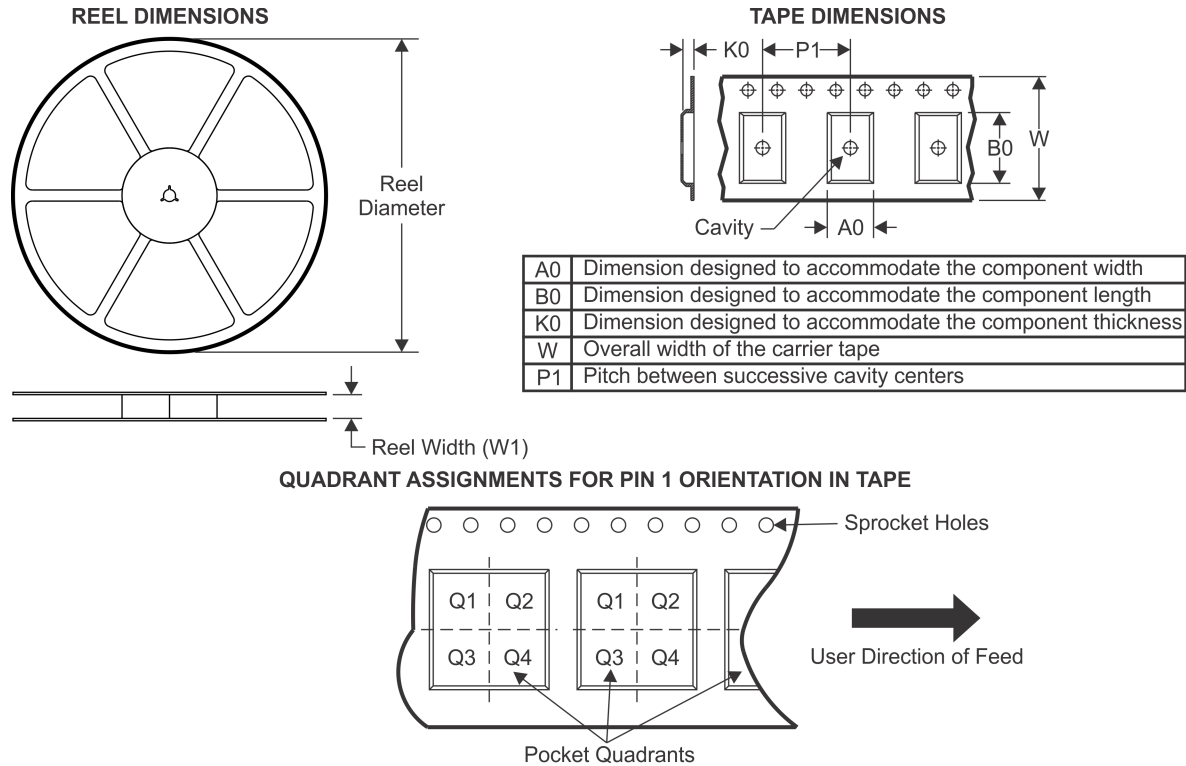
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications



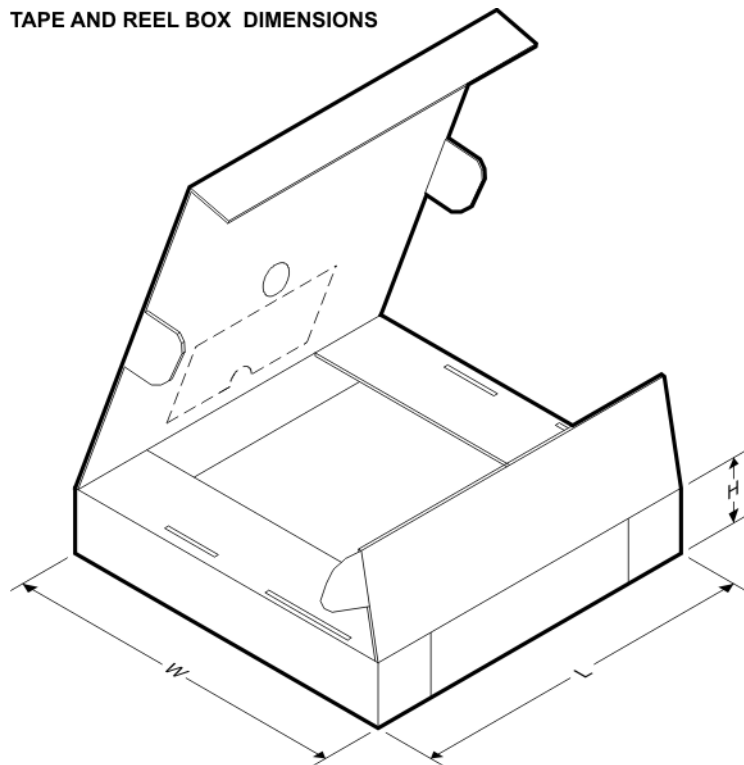
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

| Device         | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74AHCT374DBR | SSOP         | DB              | 20   | 2000 | 330.0              | 16.4               | 8.2     | 7.5     | 2.5     | 12.0    | 16.0   | Q1            |
| SN74AHCT374DWR | SOIC         | DW              | 20   | 2000 | 330.0              | 24.4               | 10.8    | 13.3    | 2.7     | 12.0    | 24.0   | Q1            |
| SN74AHCT374PWR | TSSOP        | PW              | 20   | 2000 | 330.0              | 16.4               | 6.95    | 7.1     | 1.6     | 8.0     | 16.0   | Q1            |

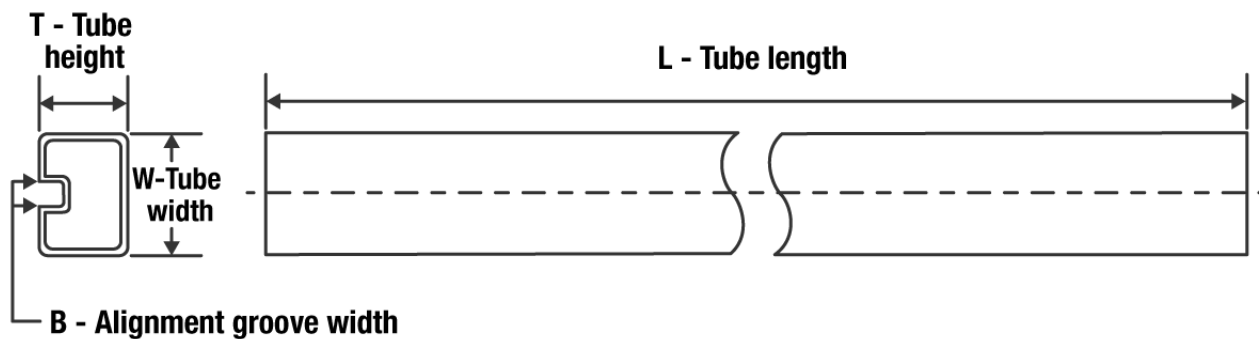
## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device         | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74AHCT374DBR | SSOP         | DB              | 20   | 2000 | 853.0       | 449.0      | 35.0        |
| SN74AHCT374DWR | SOIC         | DW              | 20   | 2000 | 367.0       | 367.0      | 45.0        |
| SN74AHCT374PWR | TSSOP        | PW              | 20   | 2000 | 853.0       | 449.0      | 35.0        |

## TUBE

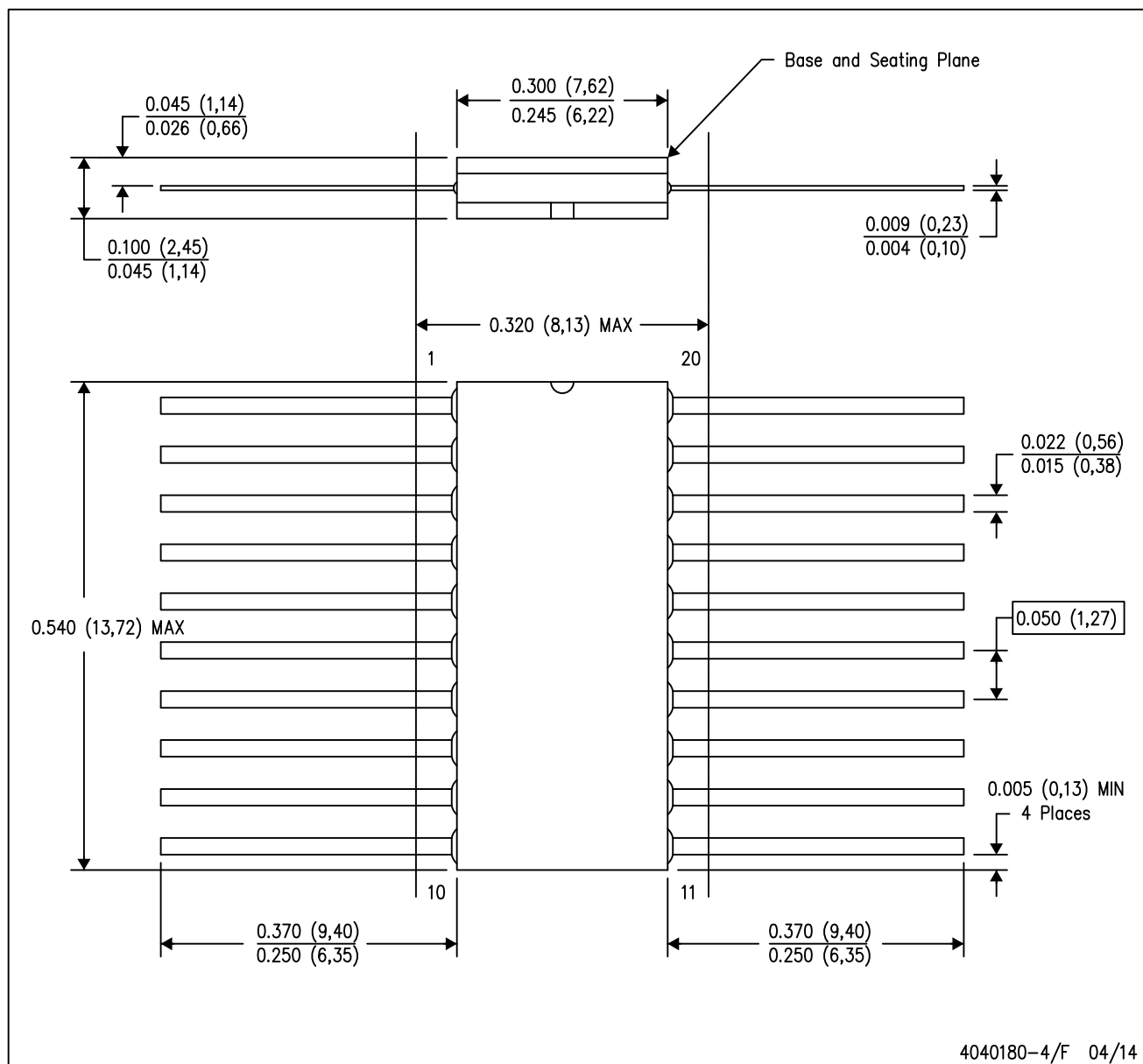


\*All dimensions are nominal

| Device          | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|-----------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| 5962-9686501Q2A | FK           | LCCC         | 20   | 1   | 506.98 | 12.06  | 2030   | NA     |
| SN74AHCT374DW   | DW           | SOIC         | 20   | 25  | 507    | 12.83  | 5080   | 6.6    |
| SN74AHCT374N    | N            | PDIP         | 20   | 20  | 506    | 13.97  | 11230  | 4.32   |
| SN74AHCT374PW   | PW           | TSSOP        | 20   | 70  | 530    | 10.2   | 3600   | 3.5    |
| SNJ54AHCT374FK  | FK           | LCCC         | 20   | 1   | 506.98 | 12.06  | 2030   | NA     |

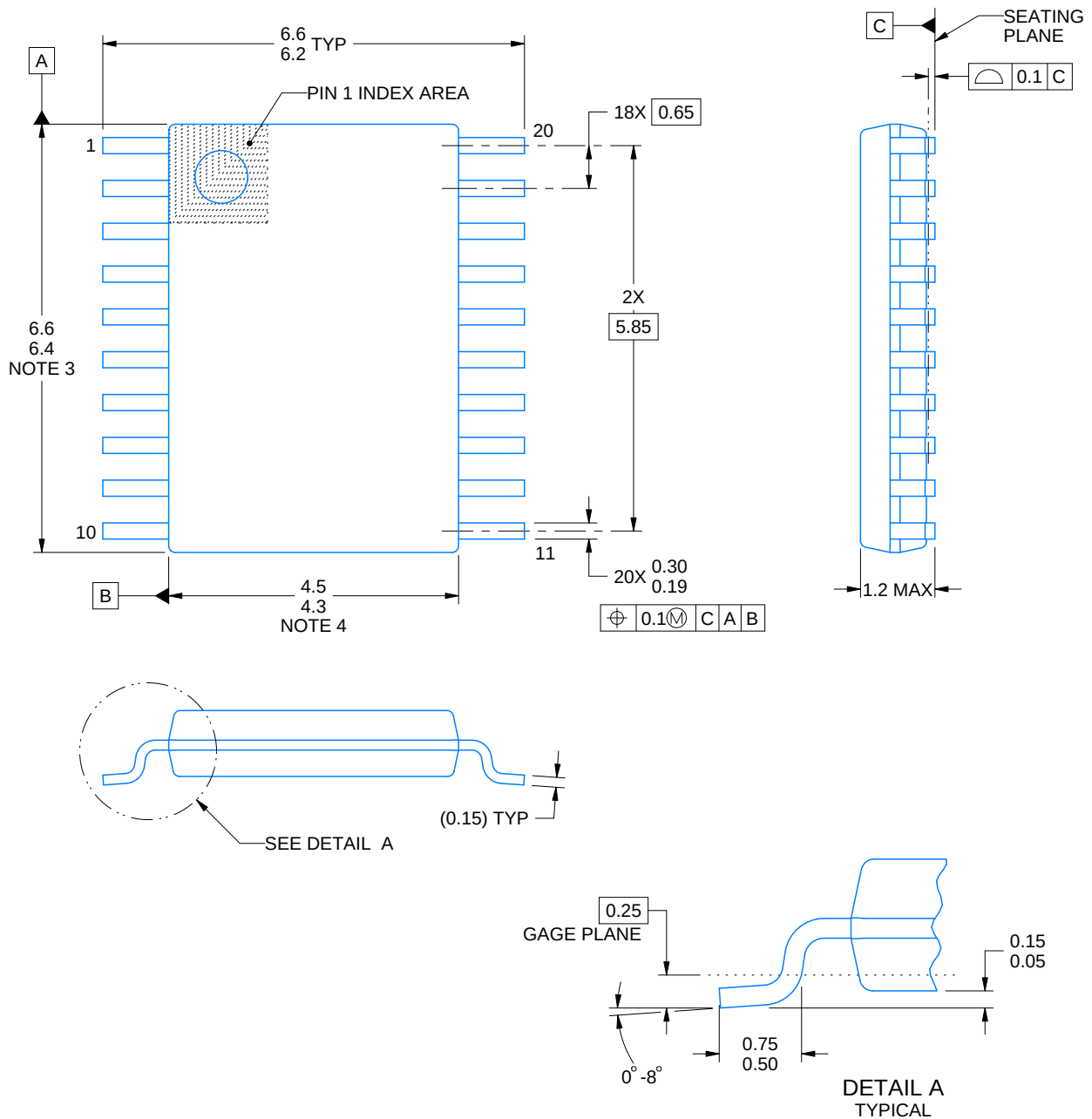
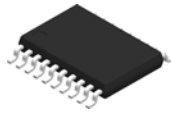
W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



## NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



4220206/A 02/2017

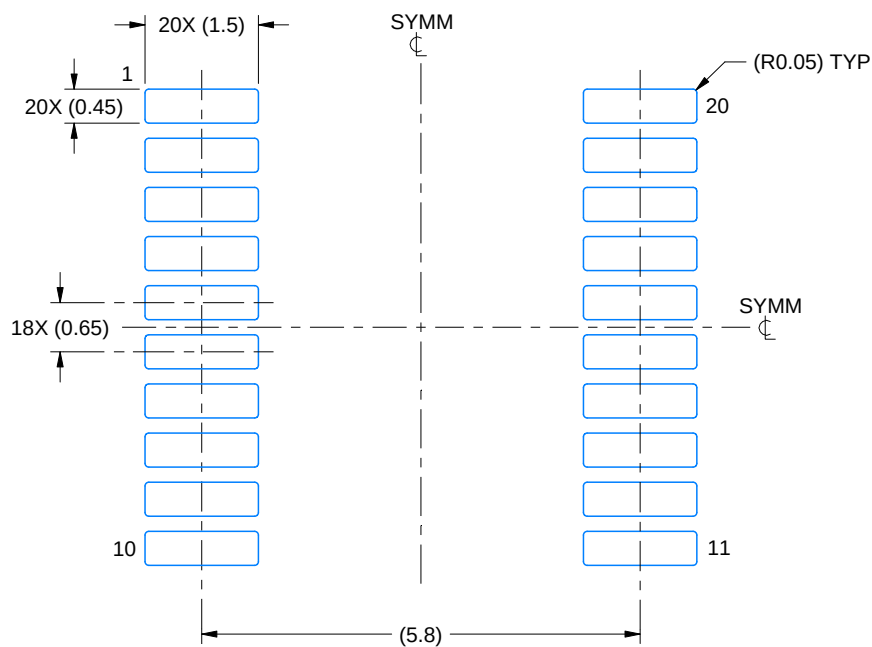
## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

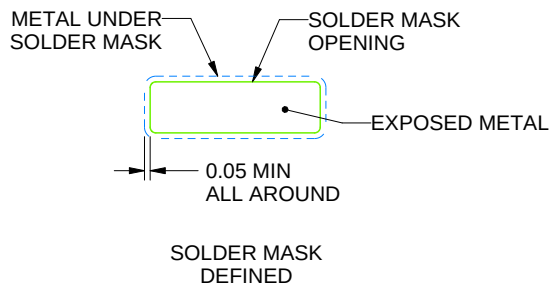
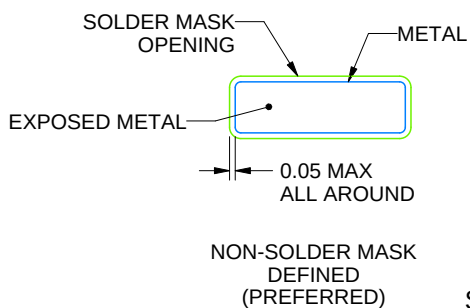
**PW0020A**

**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



## SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

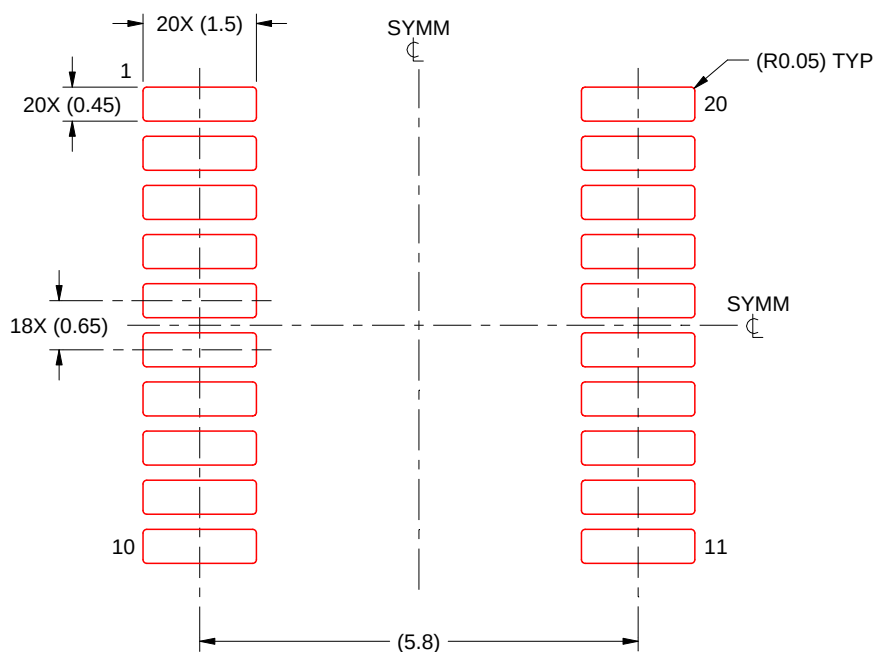
6. Publication IPC-7351 may have alternate designs.  
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

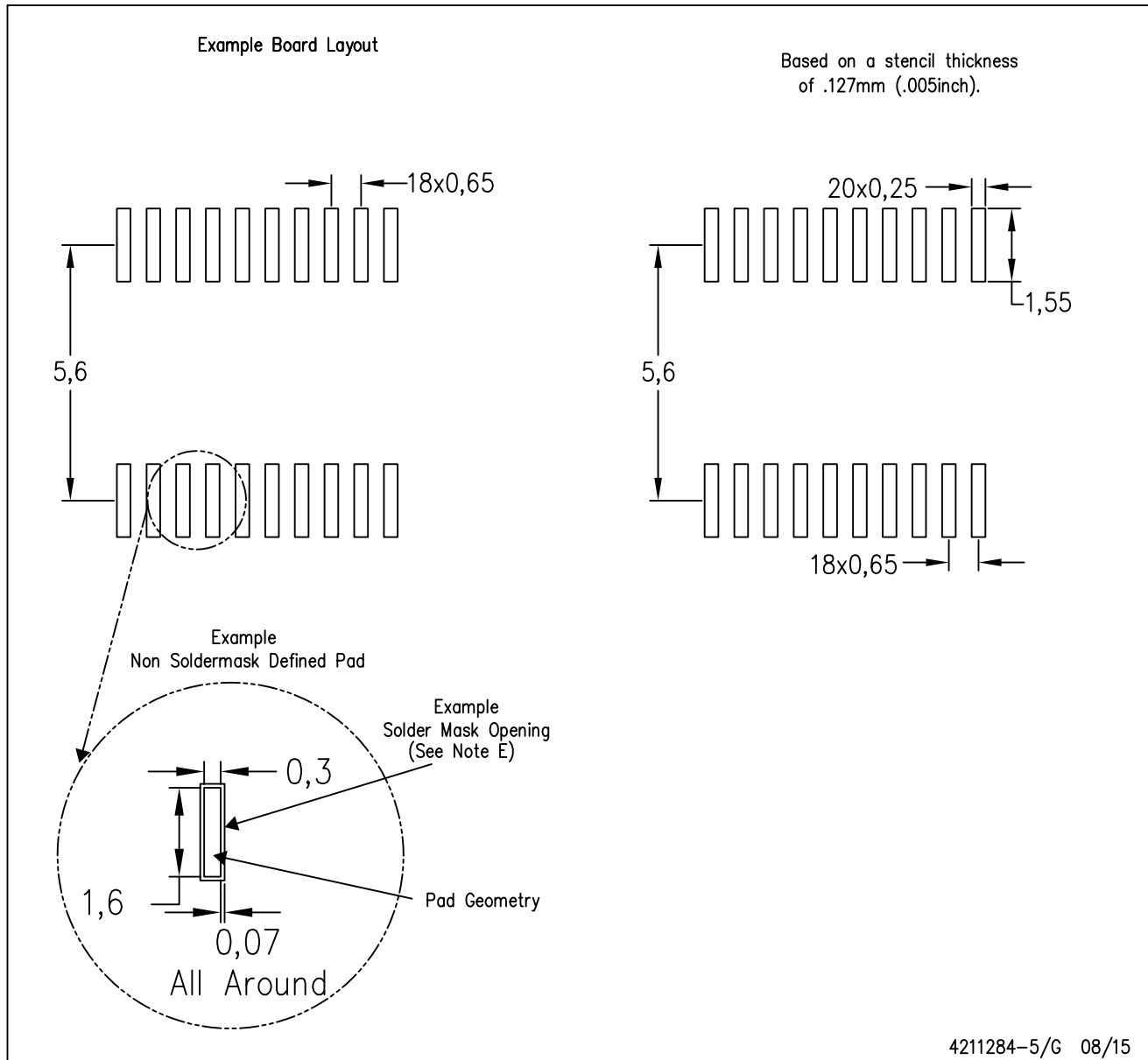
4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



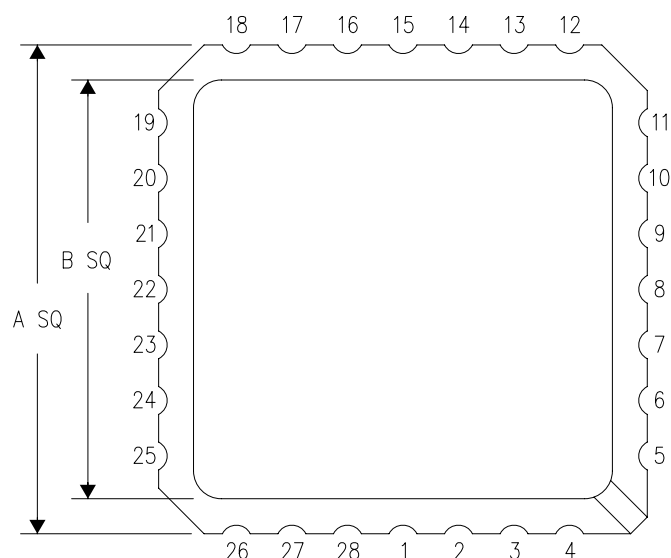
- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



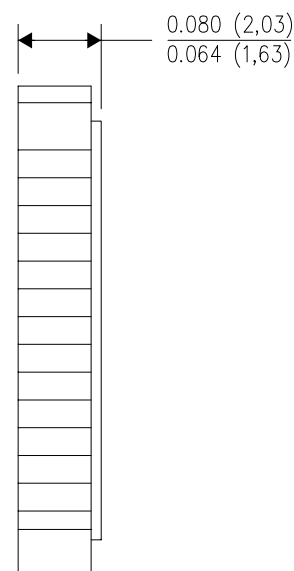
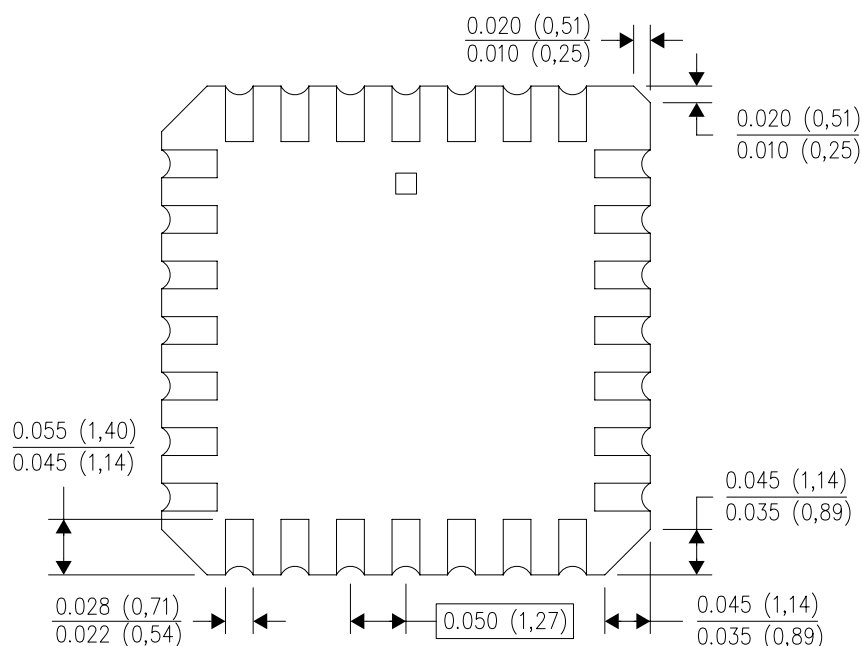
FK (S-CQCC-N\*\*)

28 TERMINAL SHOWN

# LEADLESS CERAMIC CHIP CARRIER



| NO. OF<br>TERMINALS<br>** | A                |                  | B                |                  |
|---------------------------|------------------|------------------|------------------|------------------|
|                           | MIN              | MAX              | MIN              | MAX              |
| 20                        | 0.342<br>(8,69)  | 0.358<br>(9,09)  | 0.307<br>(7,80)  | 0.358<br>(9,09)  |
| 28                        | 0.442<br>(11,23) | 0.458<br>(11,63) | 0.406<br>(10,31) | 0.458<br>(11,63) |
| 44                        | 0.640<br>(16,26) | 0.660<br>(16,76) | 0.495<br>(12,58) | 0.560<br>(14,22) |
| 52                        | 0.740<br>(18,78) | 0.761<br>(19,32) | 0.495<br>(12,58) | 0.560<br>(14,22) |
| 68                        | 0.938<br>(23,83) | 0.962<br>(24,43) | 0.850<br>(21,6)  | 0.858<br>(21,8)  |
| 84                        | 1.141<br>(28,99) | 1.165<br>(29,59) | 1.047<br>(26,6)  | 1.063<br>(27,0)  |



4040140/D 01/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

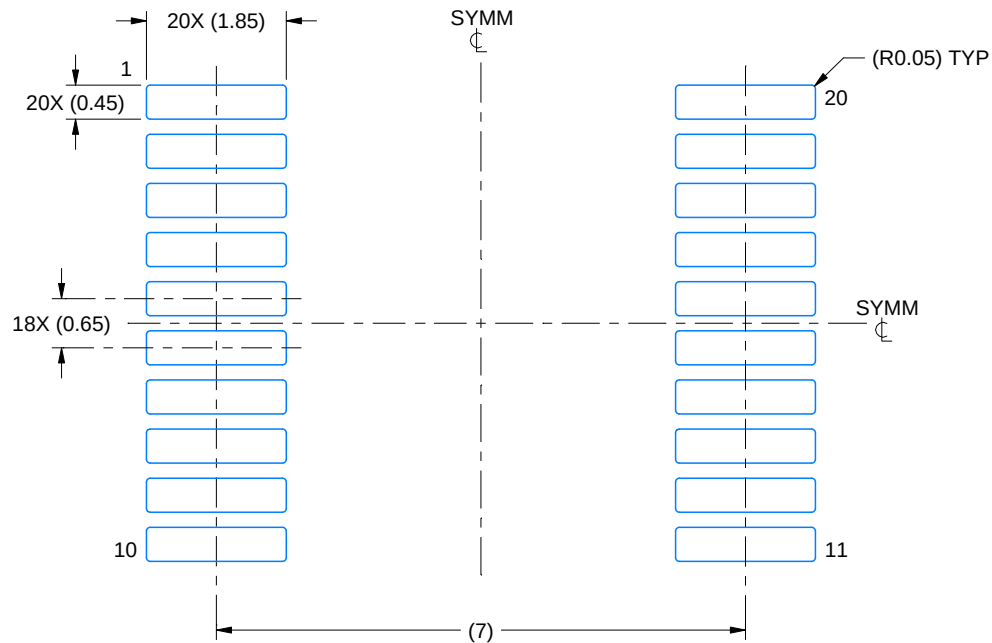


# EXAMPLE BOARD LAYOUT

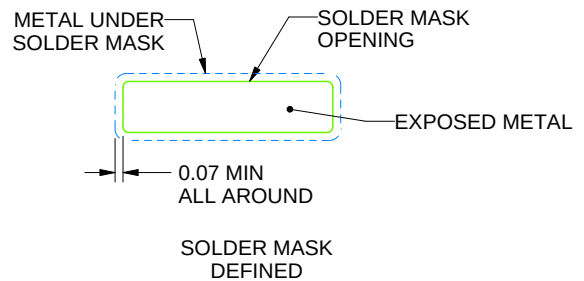
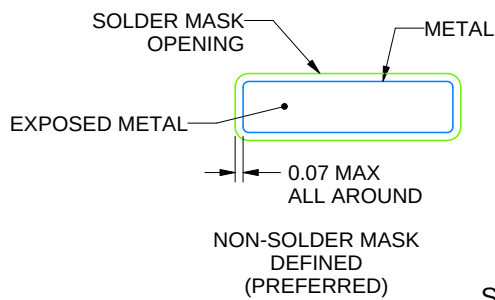
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

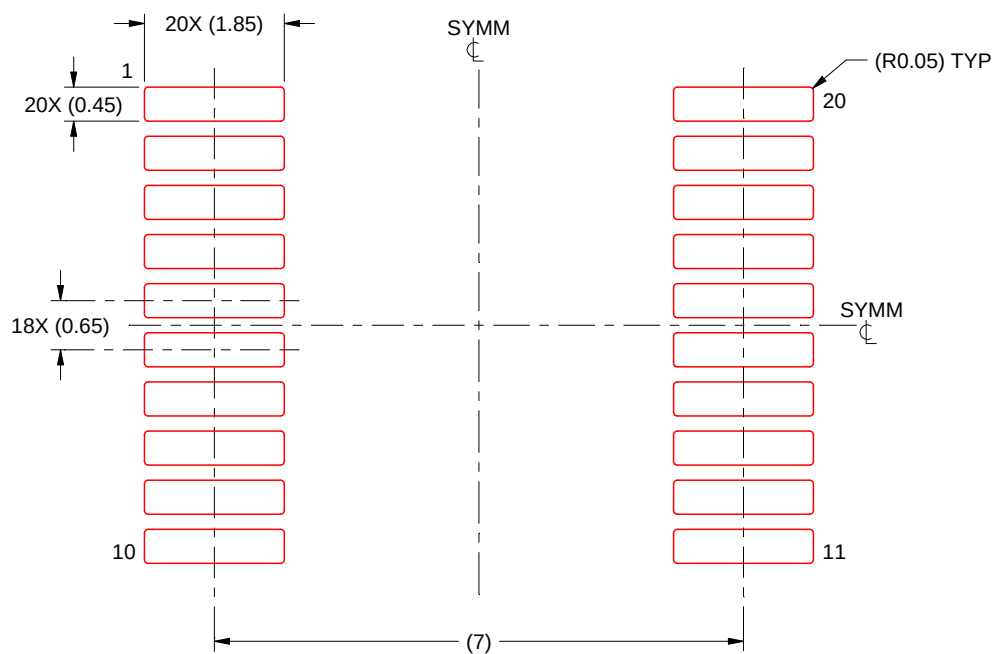
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4214851/B 08/2019

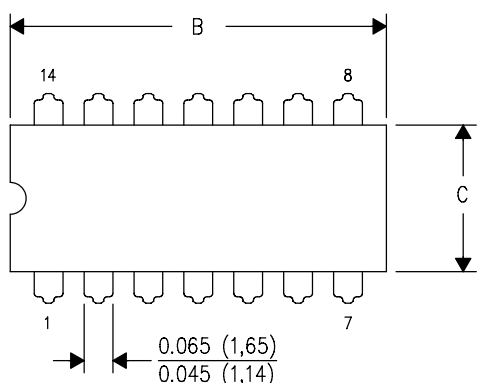
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

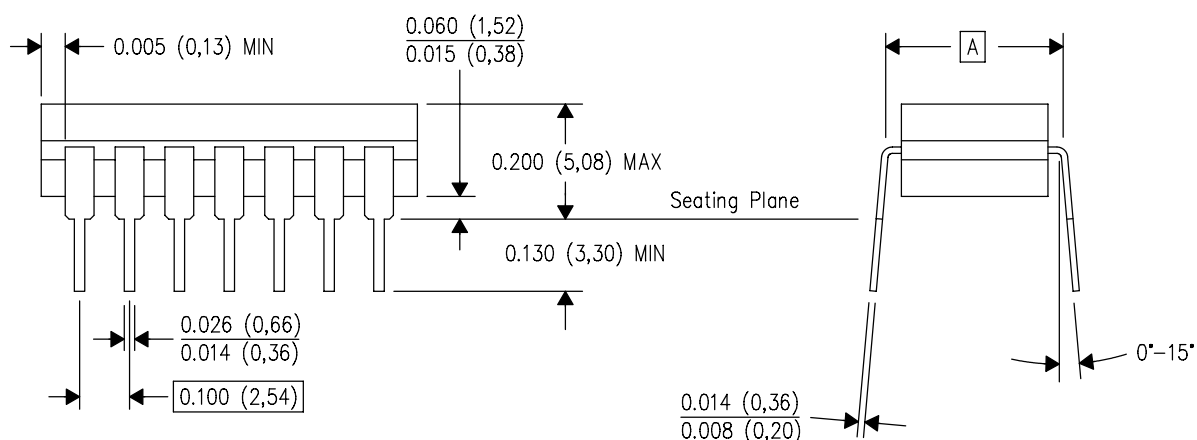
J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



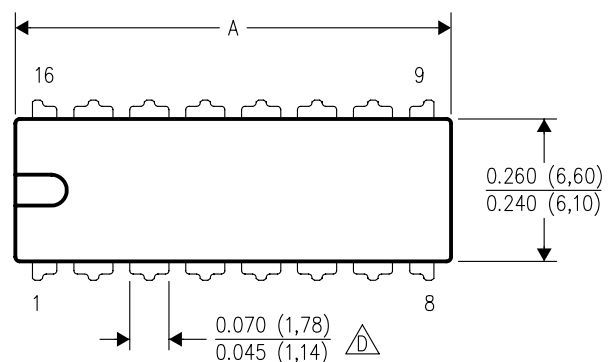
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

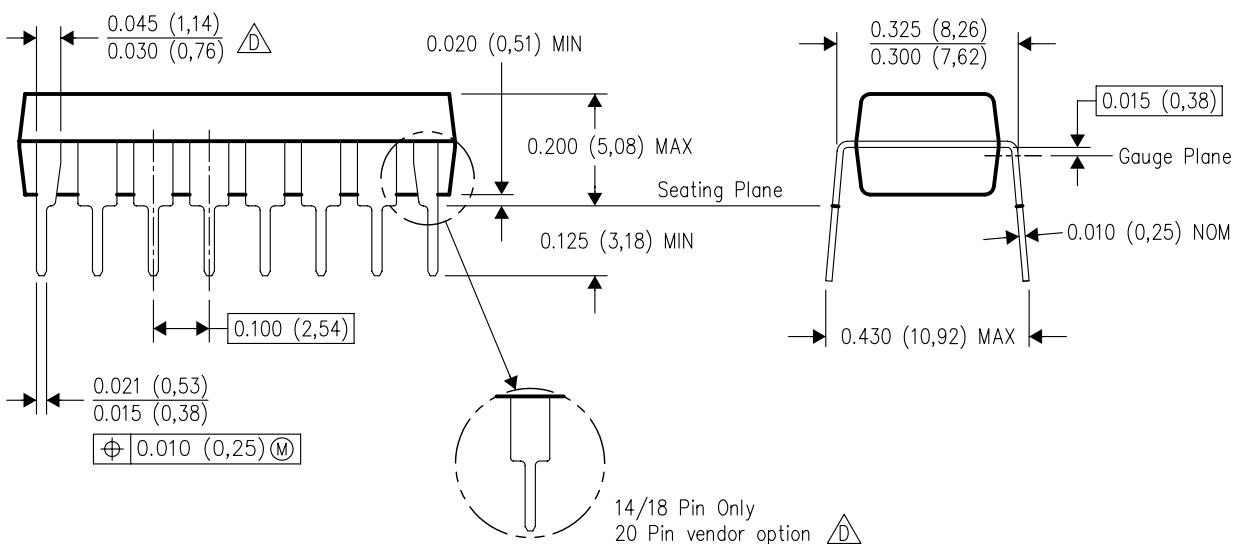
N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



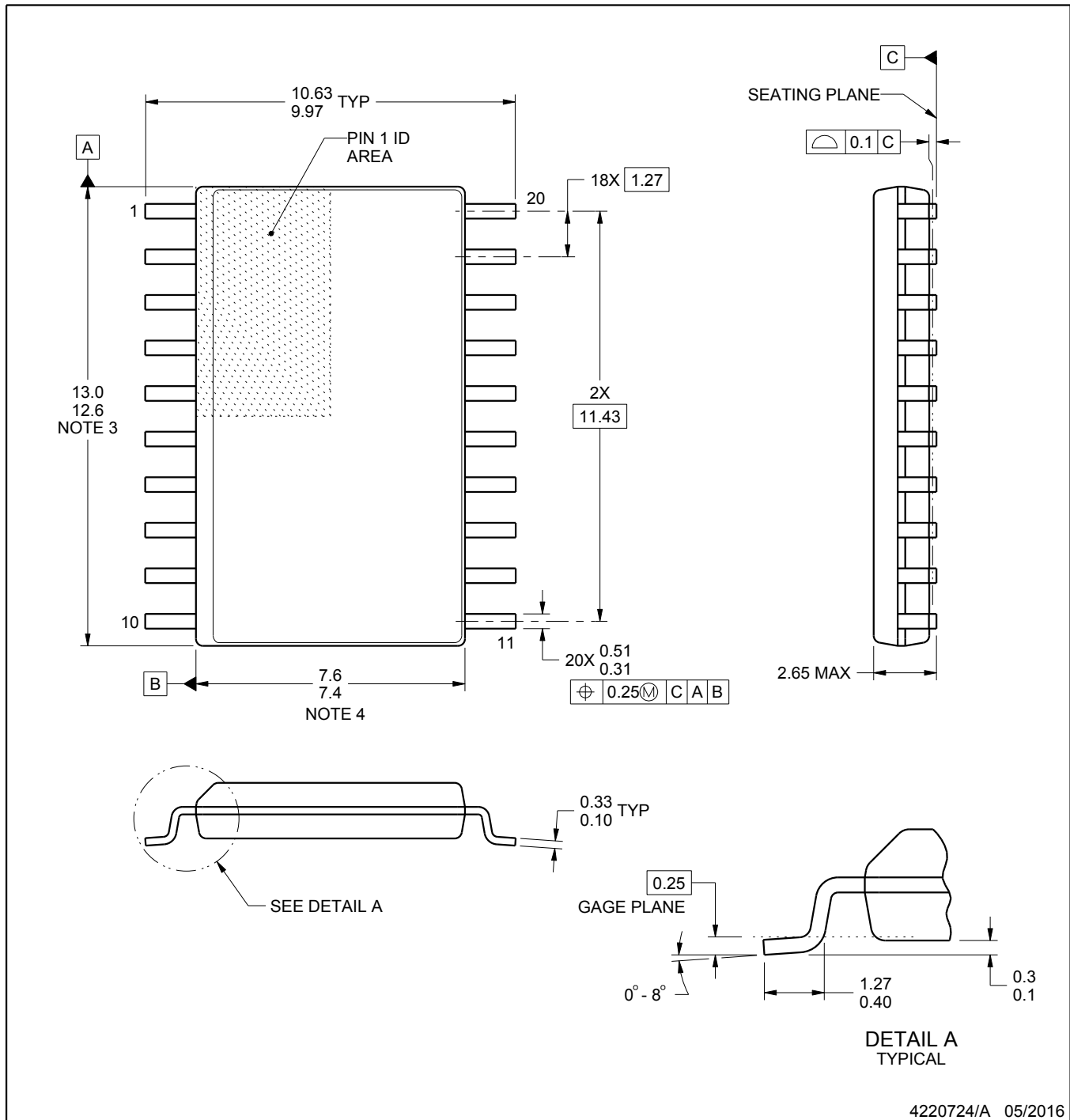
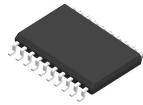
| PINS **<br>DIM      | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 The 20 pin end lead shoulder width is a vendor option, either half or full width.



## NOTES:

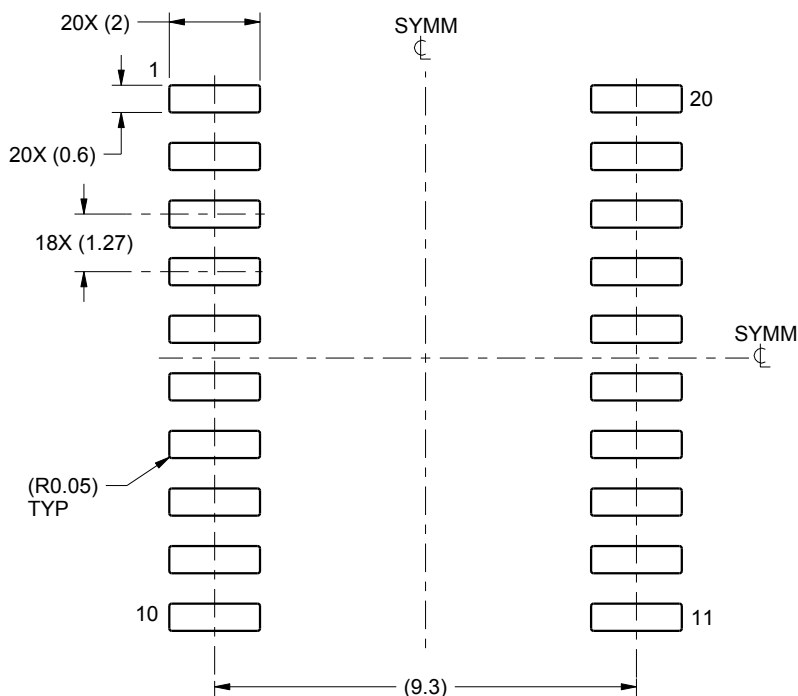
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

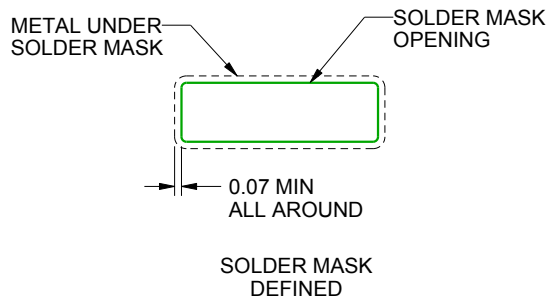
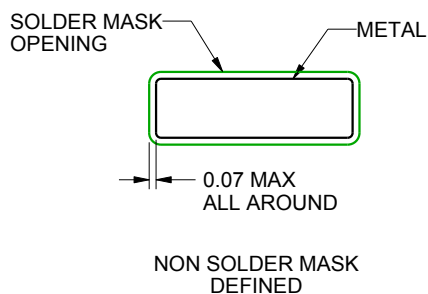
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

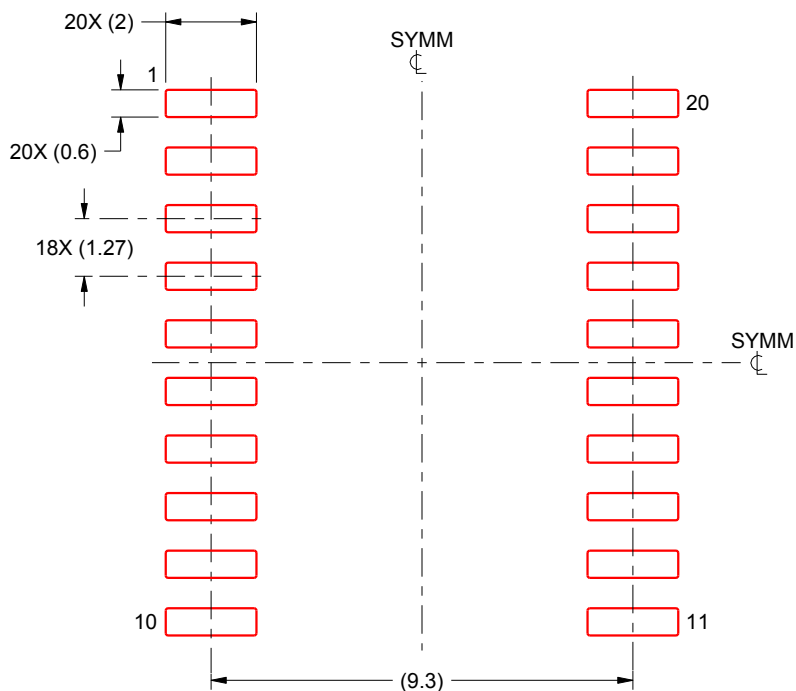


## EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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